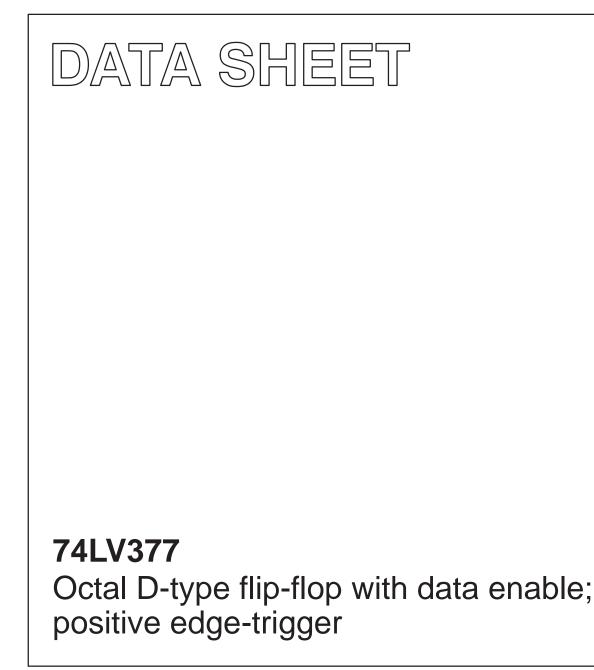
INTEGRATED CIRCUITS



Product specification Supersedes data of 1997 Mar 04 IC24 Data Handbook 1998 Jun 10



Philips Semiconductors

74LV377

FEATURES

- Optimized for Low Voltage applications: 1.0 to 3.6V
- Accepts TTL input levels between V_{CC} = 2.7V and V_{CC} = 3.6V
- Typical V_{OLP} (output ground bounce) < 0.8V @ V_{CC} = 3.3V, T_{amb} = 25°C
- Typical V_{OHV} (output V_{OH} undershoot) > 2V @ V_{CC} = 3.3V, T_{amb} = 25°C
- Ideal for addressable register applications
- Data enable for address and data synchronization applications
- Eight positive-edge triggered D-type flip-flops
- Output capability: standard
- I_{CC} category: MSI

QUICK REFERENCE DATA

GND = 0V; $T_{amb} = 25^{\circ}C$; $t_r = t_f \le 2.5$ ns

DESCRIPTION

The 74LV377 is a low–voltage CMOS device and is pin and function compatible with 74HC/HCT377.

The 74LV377 has eight edge-triggered, D-type flip-flops with individual D inputs and Q outputs. A common clock (CP) input loads all flip-flops simultaneously when the data enable (\overline{E}) is LOW. The state of each D input, one set-up time before the LOW-to-HIGH clock transition, is transferred to the corresponding output (Q_n) of the flip-flop. The \overline{E} input must be stable only one set-up time prior to the LOW-to-HIGH transition for predictable operation.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} /t _{PLH}	Propagation delay CP to Q _n	C _L = 15pF	13	ns
f _{max}	Maximum clock frequency	$V_{CC} = 3.3V$	77	MHz
Cl	Input capacitance		3.5	pF
C _{PD}	Power dissipation capacitance per flip-flop	Notes 1 and 2	20	pF

NOTES:

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μ W) $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where: f_i = input frequency in MHz; C_L = output load capacity in pF; f_o = output frequency in MHz; V_{CC} = supply voltage in V; $\Sigma (C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

2. The condition is $V_I = GND$ to V_{CC}

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
20-Pin Plastic DIL	–40°C to +125°C	74LV377 N	74LV377 N	SOT146-1
20-Pin Plastic SO	–40°C to +125°C	74LV377 D	74LV377 D	SOT163-1
20-Pin Plastic SSOP Type II	–40°C to +125°C	74LV377 DB	74LV377 DB	SOT339-1
20-Pin Plastic TSSOP Type I	–40°C to +125°C	74LV377 PW	74LV377PW DH	SOT360-1

PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION					
1	Ē	Data enable input (active-LOW)					
2, 5, 6, 9, 12, 15, 16, 19 Q ₀ to Q ₇		flip-flop outputs					
3, 4, 7, 8, 13, 14, 17, 18	D ₀ to D ₇	Data inputs					
10	GND	Ground (0V)					
11	СР	Clock input (LOW-to-HIGH, edge-triggered)					
20	V _{CC}	Positive supply voltage					

FUNCTION TABLE

OPERATING MODES		NPUTS	;	OUTPUTS		
OPERATING MODES	СР	Ē	D _n	Q _n		
Load "1"	↑	Ι	h	Н		
Load "0"	↑	Ι	Ι	L		
Hold (do nothing)	↑ X	h H	X X	No change No change		

H = HIGH voltage level

 HIGH voltage level one set-up time prior to the LOW-to-HIGH CP transition

LOW voltage level

 LOW voltage level one set-up time prior to the LOW-to-HIGH CP transition

LOW-to-HIGH CP transition

= Don't care

h

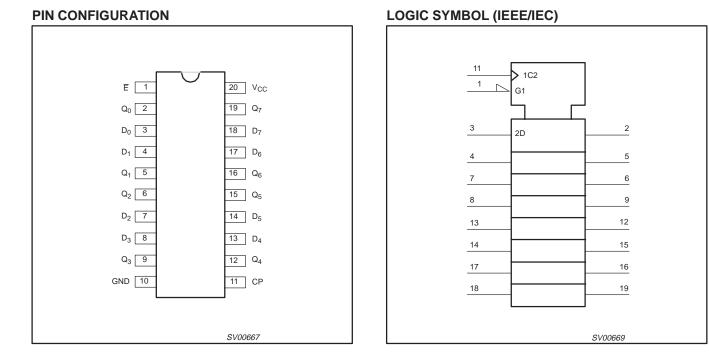
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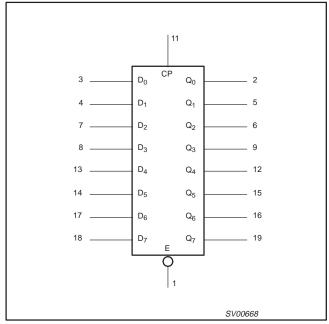
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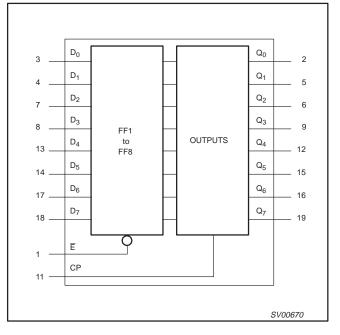
74LV377



LOGIC SYMBOL



FUNCTIONAL DIAGRAM



74LV377

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
V _{CC}	DC supply voltage	See Note 1	1.0	3.3	3.6	V
VI	Input voltage		0	-	V _{CC}	V
Vo	Output voltage		0	-	V _{CC}	V
T _{amb}	Operating ambient temperature range in free air	See DC and AC characteristics	-40 -40		+85 +125	°C
t _r , t _f	Input rise and fall times	$\begin{array}{l} V_{CC} = 1.0 \text{V to } 2.0 \text{V} \\ V_{CC} = 2.0 \text{V to } 2.7 \text{V} \\ V_{CC} = 2.7 \text{V to } 3.6 \text{V} \end{array}$			500 200 100	ns/V

NOTE:

1. The LV is guaranteed to function down to V_{CC} = 1.0V (input levels GND or V_{CC}); DC characteristics are guaranteed from V_{CC} = 1.2V to V_{CC} = 3.6V.

ABSOLUTE MAXIMUM RATINGS^{1, 2}

In accordance with the Absolute Maximum Rating System (IEC 134).

Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +4.6	V
±I _{IK}	DC input diode current	$V_{I} < -0.5 \text{ or } V_{I} > V_{CC} + 0.5 V$	20	mA
±I _{OK}	DC output diode current	V_{O} < -0.5 or V_{O} > V_{CC} + 0.5V	50	mA
±IO	DC output source or sink current – standard outputs	$-0.5V < V_O < V_{CC} + 0.5V$	25	mA
±I _{GND} , ±I _{CC}	DC V _{CC} or GND current for types with -standard outputs		50	mA
T _{stg}	Storage temperature range		-65 to +150	°C
P _{tot}	Power dissipation per package –plastic DIL –plastic mini-pack (SO) –plastic shrink mini-pack (SSOP and TSSOP)	for temperature range: -40 to +125°C above +70°C derate linearly with 12mW/K above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	750 500 400	mW

NOTES:

 Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

DC CHARACTERISTICS FOR THE LV FAMILY

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

					LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	-4	0°C to +8	5°C	-40°C to	o +125°C	
			MIN	TYP ¹	MAX	MIN	MAX	1
		$V_{CC} = 1.2V$	0.9			0.9		
VIH	HIGH level Input voltage	$V_{CC} = 2.0V$	1.4			1.4		V
		V _{CC} = 2.7 to 3.6V	2.0			2.0		1
		V _{CC} = 1.2V			0.3		0.3	
VIL	LOW level Input voltage	$V_{CC} = 2.0 V$			0.6		0.6	V
	Voltage	V _{CC} = 2.7 to 3.6V			0.8		0.8	1
		$V_{CC} = 1.2V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$		1.2				
V _{OH}	HIGH level output	$V_{CC} = 2.0V; V_I = V_{IH} \text{ or } V_{IL;} - I_O = 100 \mu A$	1.8	2.0		1.8		1
	voltage; all outputs	$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL;} - I_O = 100 \mu A$	2.5	2.7		2.5	1	1
		$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}, -I_O = 100 \mu A$	2.8	3.0		2.8	1	V
	HIGH level output voltage; STANDARD outputs	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} - I_O = 6mA$	2.40	2.82		2.20]
		V_{CC} = 1.2V; V_I = V_{IH} or V_{IL} ; I_O = 100 μ A		0				
	LOW level output	V_{CC} = 2.0V; V_I = V_{IH} or $V_{IL;} I_O$ = 100 μ A		0	0.2		0.2	
	voltage; all outputs	V_{CC} = 2.7V; V_I = V_{IH} or $V_{IL;} I_O$ = 100 μ A		0	0.2		0.2	7
V _{OL}		V_{CC} = 3.0V; V_I = V_{IH} or $V_{IL;} I_O$ = 100 μ A		0	0.2		0.2	V
	LOW level output voltage; STANDARD outputs	V_{CC} = 3.0V; V_I = V_{IH} or V_{IL} ; I_O = 6mA		0.25	0.40		0.50	
I _I	Input leakage current	$V_{CC} = 3.6V; V_I = V_{CC} \text{ or GND}$			1.0		1.0	μA
I _{CC}	Quiescent supply current; MSI	$V_{CC} = 3.6V; V_I = V_{CC} \text{ or } \text{GND}; I_O = 0$			20.0		160	μΑ
ΔI_{CC}	Additional quiescent supply current per input	$V_{CC} = 2.7V$ to 3.6V; $V_I = V_{CC} - 0.6V$			500		850	μΑ

NOTE:

1. All typical values are measured at $T_{amb} = 25^{\circ}C$.

AC CHARACTERISTICS

 $GND = 0V; \ t_r = t_f \leq 2.5 ns; \ C_L = 50 pF; \ R_L = 1 K \Omega$

			CONDITION			LIMITS			
SYMBOL	PARAMETER	WAVEFORM	CONDITION	_	40 to +85 °	C	-40 to	+125 °C	UNIT
			V _{CC} (V)	MIN	TYP ¹	MAX	MIN	MAX	
			1.2	-	80	-	-	-	
	Propagation delay		2.0	-	27	51	-	61	
t _{PHL} /t _{PLH}	CP to Q _n	Figure 1	2.7	-	20	38	-	45	ns
			3.0 to 3.6	-	15 ²	30	-	36	
			2.0	34	9	-	41	-	
t _W	Clock pulse width HIGH or LOW	Figure 2	2.7	25	6	-	30	-	ns
		3.0 to 3.6	20	5 ²	-	24	-		
		1.2	-	25	-	-	-		
	t _{su} Set-up time D _n to CP		2.0	22	9	-	26	-	
t _{su}		Figure 2	2.7	16	6	-	19	-	ns
			3.0 to 3.6	13	5 ²	-	15	-	
			1.2	-	10	-	-	-	
	Set-up time		2.0	22	4	-	26	-	
t _{su}	E to CP	Figure 2	2.7	16	3	-	19	-	ns
			3.0 to 3.6	13	2 ²	-	15	-	
			1.2	-	-15	-	-	-	
	Hold time		2.0	5	-5	-	5	-	
t _h	D _n to CP	Figure 2	2.7	5	-4	-	5	-	ns
			3.0 to 3.6	5	-3 ²	-	5	-	
			1.2	-	-5	-	-	-	
4	Hold time		2.0	5	-2	-	5	-	
t _h	E to CP	Figure 2	2.7	5	-2	-	5	-	ns
			3.0 to 3.6	5	-1 ²	-	5	-	
			2.0	14	40	-	12	-	
f _{max}	Maximum clock pulse frequency	Figure 1	2.7	19	58	-	16	-	MHz
	, ,,		3.0 to 3.6	24	70 ²	- 1	20	- 1	

NOTES:

1. Unless otherwise stated, all typical values are at $T_{amb} = 25^{\circ}C$. 2. Typical value measured at $V_{CC} = 3.3V$.

74LV377

AC WAVEFORMS

 V_M = 1.5V at $V_{CC} \ge 2.7V$ V_M = 0.5V * V_{CC} at $V_{CC} < 2.7V$ V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

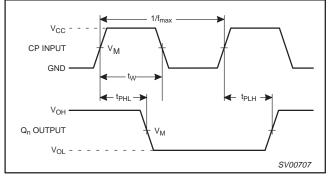
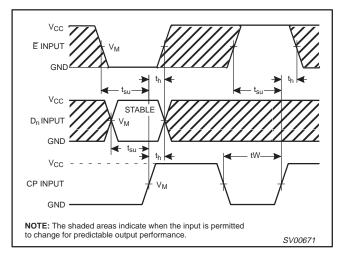
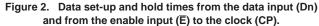


Figure 1. Clock (CP) to output (Q_n) propagation delays, the clock pulse width and the maximum clock pulse frequency.





TEST CIRCUIT

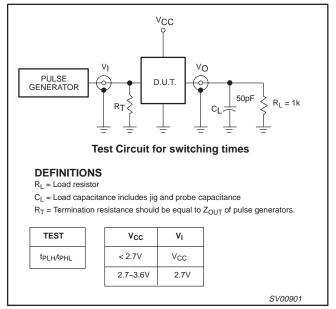


Figure 3. Load circuitry for switching times

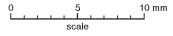
seating plane

Octal D-type flip-flop with data enable; positive edge-trigger

74LV377

Μ_H

SOT146-1 DIP20: plastic dual in-line package; 20 leads (300 mil) M_{E} Ш A'1 ⊕ w M b₁



10

DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

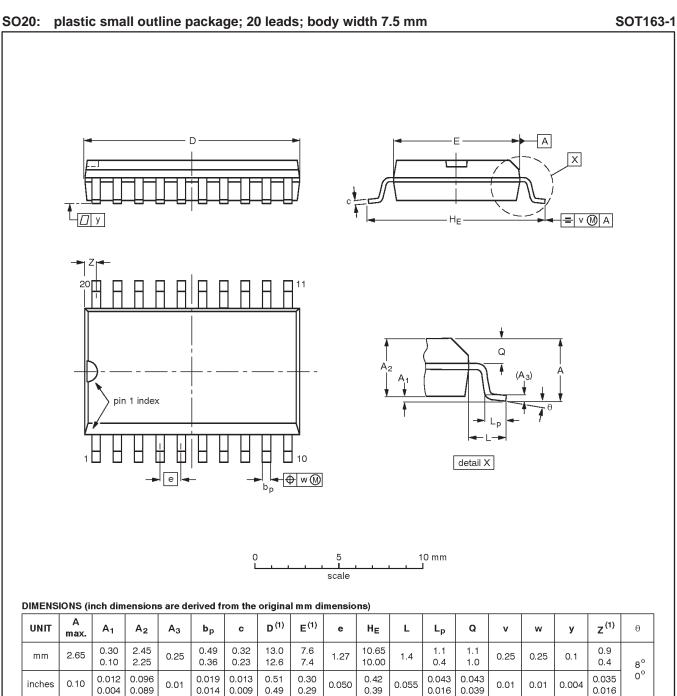
OUTLINE		REFEF	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1550E DATE
SOT146-1			SC603			-92-11-17 95-05-24

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pin 1 index

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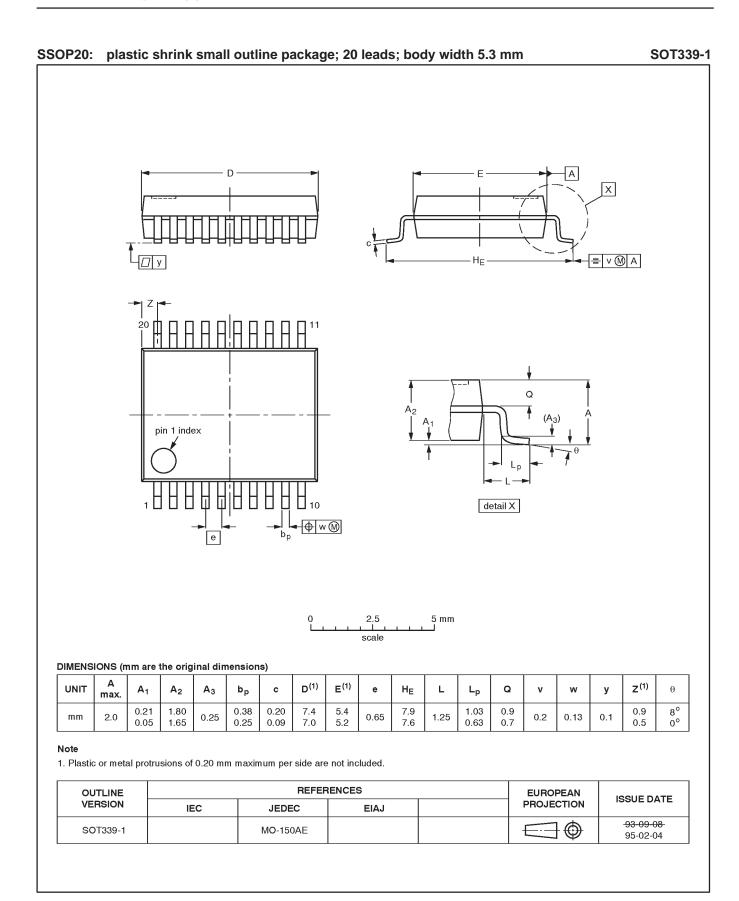
Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

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VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT163-1	075E04	MS-013AC			-92-11-17 95-01-24

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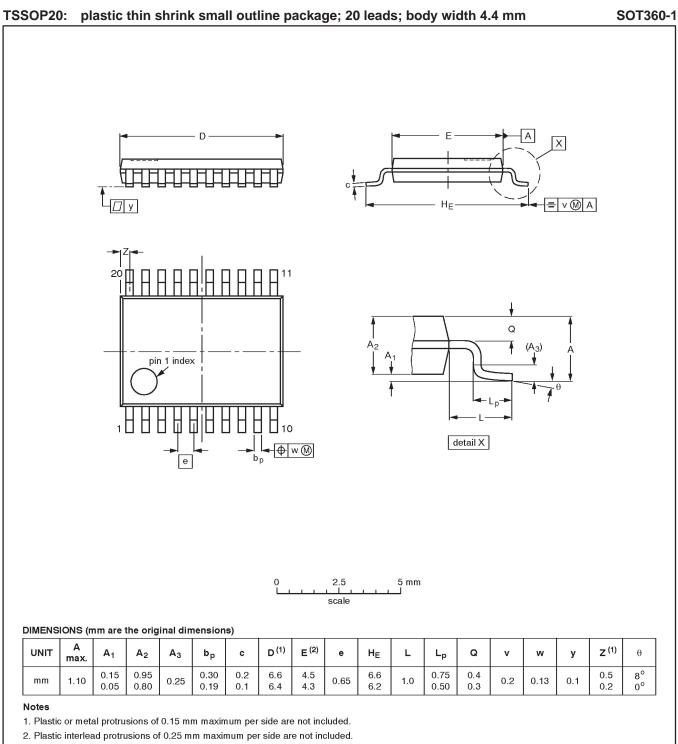
Product specification



Product specification

Octal D-type flip-flop with data enable; positive edge-trigger

74LV377



OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT360-1		MO-153AC				-93-06-16 95-02-04

74LV377

DEFINITIONS		
Data Sheet Identification	Product Status	Definition
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
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